## **Technical Data**



# Resicure™ EMI-24 and EMI-24LV

### **Description:**

EMI-24 is commonly used as a sole curing agent or as a dicy and anhydride cure accelerator in epoxy resin based formulations. Typical loading level as a sole curing agent is about 1-5 phr and as a dicy and anhydride cure accelerator is about 0.5-3.0 phr.

Resicure EMI-24 LV is a lower viscosity version of Resicure EMI-24.

#### **Advantages:**

- Rapid reactivity at temperature <100°C with 9-12 hours latency
- High glass transition temperature
- High chemical resistance

#### **Typical Applications:**

- One-component adhesives for electronics applications
- Composites such as pre-pregs and filament winding
- Electrical potting and encapsulation

#### **Handling Precautions:**

Refer to the product Safety Data Sheet

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2-ethyl-4-methylimidazole

<b>Typical Properties:</b>	EMI-24	EMI-24 LV
Appearance:	Amber to brownish	
	liquid	
Viscosity (@25°C):	9600 cPs	1000 cPs
Gardner color:	16 max.	15 max.
Moisture content:	<0.4%	< 0.4%
Assav:	> 85%	>83%

Recommended use level with

Epoxy resin (EEW=190): 1-5 PHR

#### **Typical Performance:**

Gel time @ 100°C: 7.0 minutes
Gel time @ 150°C: 1.0 minutes
Latency at 25°C: 9-12 hours
HDT: 163°C